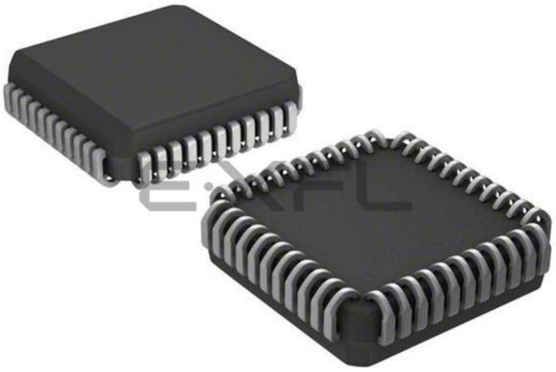

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	4MHz
Connectivity	I²C, SPI
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	33
Program Memory Size	3.5KB (2K x 14)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	128 x 8
Voltage - Supply (Vcc/Vdd)	2.5V ~ 6V
Data Converters	-
Oscillator Type	External
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-LCC (J-Lead)
Supplier Device Package	44-PLCC (16.59x16.59)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16lc64a-04i-l

TABLE 5-11: PORTE FUNCTIONS

Name	Bit#	Buffer Type	Function
RE0/$\overline{RD}$	bit0	ST/TTL(1)	Input/output port pin or Read control input in parallel slave port mode. $\overline{RD}$ 1 = Not a read operation 0 = Read operation. The system reads the PORTD register (if chip selected)
RE1/$\overline{WR}$	bit1	ST/TTL(1)	Input/output port pin or Write control input in parallel slave port mode. $\overline{WR}$ 1 = Not a write operation 0 = Write operation. The system writes to the PORTD register (if chip selected)
RE2/$\overline{CS}$	bit2	ST/TTL(1)	Input/output port pin or Chip select control input in parallel slave port mode. $\overline{CS}$ 1 = Device is not selected 0 = Device is selected

Legend: ST = Schmitt Trigger input, TTL = TTL input
Note 1: Buffer is a Schmitt Trigger when in I/O mode, and a TTL buffer when in Parallel Slave Port (PSP) mode.

TABLE 5-12: SUMMARY OF REGISTERS ASSOCIATED WITH PORTE

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR	Value on all other resets
09h	PORTE	—	—	—	—	—	RE2	RE1	RE0	`---- -xxx`	`---- -uuu`
89h	TRISE	IBF	OBF	IBOV	PSPMODE	—	PORTE Data Direction Bits			`0000 -111`	`0000 -111`

Legend: `x` = unknown, `u` = unchanged, `-` = unimplemented locations read as '0'. Shaded cells not used by PORTE.

8.0 TIMER1 MODULE

Applicable Devices													
61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67

Timer1 is a 16-bit timer/counter consisting of two 8-bit registers (TMR1H and TMR1L) which are readable and writable. Register TMR1 (TMR1H:TMR1L) increments from 0000h to FFFFh and rolls over to 0000h. The TMR1 Interrupt, if enabled, is generated on overflow which is latched in interrupt flag bit TMR1IF (PIR1<0>). This interrupt can be enabled/disabled by setting/clearing the TMR1 interrupt enable bit TMR1IE (PIE1<0>).

Timer1 can operate in one of two modes:

- As a timer
- As a counter

The operating mode is determined by clock select bit, TMR1CS (T1CON<1>) (Figure 8-2).

In timer mode, Timer1 increments every instruction cycle. In counter mode, it increments on every rising edge of the external clock input.

Timer1 can be enabled/disabled by setting/clearing control bit TMR1ON (T1CON<0>).

Timer1 also has an internal “reset input”. This reset can be generated by CCP1 or CCP2 (Capture/Compare/PWM) module. See Section 10.0 for details. Figure 8-1 shows the Timer1 control register.

For the PIC16C62A/R62/63/R63/64A/R64/65A/R65/R66/67, when the Timer1 oscillator is enabled (T1OSCEN is set), the RC1 and RC0 pins become inputs. That is, the TRISC<1:0> value is ignored.

For the PIC16C62/64/65, when the Timer1 oscillator is enabled (T1OSCEN is set), RC1 pin becomes an input, however the RC0 pin will have to be configured as an input by setting the TRISC<0> bit.

The Timer1 module also has a software programmable prescaler.

FIGURE 8-1: T1CON: TIMER1 CONTROL REGISTER (ADDRESS 10h)

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	T1CKPS1	T1CKPS0	T1OSCEN	$\overline{\text{T1SYNC}}$	TMR1CS	TMR1ON
bit7							bit0

R = Readable bit
W = Writable bit
U = Unimplemented bit, read as ‘0’
- n = Value at POR reset

bit 7-6: **Unimplemented**: Read as '0'

bit 5-4: **T1CKPS1:T1CKPS0**: Timer1 Input Clock Prescale Select bits
`11` = 1:8 Prescale value
`10` = 1:4 Prescale value
`01` = 1:2 Prescale value
`00` = 1:1 Prescale value

bit 3: **T1OSCEN**: Timer1 Oscillator Enable Control bit
1 = Oscillator is enabled
0 = Oscillator is shut off
Note: The oscillator inverter and feedback resistor are turned off to eliminate power drain.

bit 2: **$\overline{\text{T1SYNC}}$**: Timer1 External Clock Input Synchronization Control bit

<u>TMR1CS = 1</u>
1 = Do not synchronize external clock input
0 = Synchronize external clock input

<u>TMR1CS = 0</u>
This bit is ignored. Timer1 uses the internal clock when TMR1CS = 0.

bit 1: **TMR1CS**: Timer1 Clock Source Select bit
1 = External clock from T1OSI (on the rising edge) (See pinouts for pin with T1OSI function)
0 = Internal clock (Fosc/4)

bit 0: **TMR1ON**: Timer1 On bit
1 = Enables Timer1
0 = Stops Timer1

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11.3.1 SSP MODULE IN SPI MODE FOR PIC16C66/67

The SPI mode allows 8-bits of data to be synchronously transmitted and received simultaneously. To accomplish communication, typically three pins are used:

- Serial Data Out (SDO) RC5/SDO
- Serial Data In (SDI) RC4/SDI/SDA
- Serial Clock (SCK) RC3/SCK/SCL

Additionally a fourth pin may be used when in a slave mode of operation:

- Slave Select ($\overline{SS}$) RA5/$\overline{SS}$

When initializing the SPI, several options need to be specified. This is done by programming the appropriate control bits in the SSPCON register (SSPCON<5:0>) and SSPSTAT<7:6>. These control bits allow the following to be specified:

- Master Mode (SCK is the clock output)
- Slave Mode (SCK is the clock input)
- Clock Polarity (Idle state of SCK)
- Clock edge (output data on rising/falling edge of SCK)
- Clock Rate (Master mode only)
- Slave Select Mode (Slave mode only)

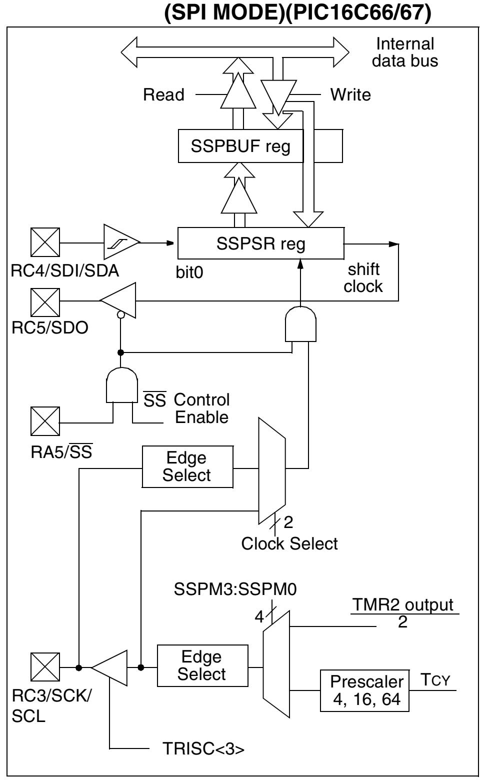
The SSP consists of a transmit/receive Shift Register (SSPSR) and a buffer register (SSPBUF). The SSPSR shifts the data in and out of the device, MSb first. The SSPBUF holds the data that was written to the SSPSR until the received data is ready. Once the 8-bits of data have been received, that byte is moved to the SSPBUF register. Then the buffer full detect bit BF (SSPSTAT<0>) and interrupt flag bit SSPIF (PIR1<3>) are set. This double buffering of the received data (SSPBUF) allows the next byte to start reception before reading the data that was just received. Any write to the SSPBUF register during transmission/reception of data will be ignored, and the write collision detect bit WCOL (SSPCON<7>) will be set. User software must clear the WCOL bit so that it can be determined if the following write(s) to the SSPBUF register completed successfully. When the application software is expecting to receive valid data, the SSPBUF should be read before the next byte of data to transfer is written to the SSPBUF. Buffer full bit BF (SSPSTAT<0>) indicates when SSPBUF has been loaded with the received data (transmission is complete). When the SSPBUF is read, bit BF is cleared. This data may be irrelevant if the SPI is only a transmitter. Generally the SSP Interrupt is used to determine when the transmission/reception has completed. The SSPBUF must be read and/or written. If the interrupt method is not going to be used, then software polling can be done to ensure that a write collision does not occur. Example 11-2 shows the loading of the SSPBUF (SSPSR) for data transmission. The shaded instruction is only required if the received data is meaningful.

EXAMPLE 11-2: LOADING THE SSPBUF (SSPSR) REGISTER (PIC16C66/67)

```
     BCF   STATUS, RP1    ;Specify Bank 1
     BSF   STATUS, RP0    ;
LOOP BTFSS SSPSTAT, BF    ;Has data been
                          ;received
                          ;(transmit
                          ;complete)?
     GOTO  LOOP           ;No
     BCF   STATUS, RP0    ;Specify Bank 0
     MOVF  SSPBUF, W      ;W reg = contents
                          ; of SSPBUF
     MOVWF RXDATA         ;Save in user RAM
     MOVF  TXDATA, W      ;W reg = contents
                          ; of TXDATA
     MOVWF SSPBUF         ;New data to xmit
```

The block diagram of the SSP module, when in SPI mode (Figure 11-9), shows that the SSPSR is not directly readable or writable, and can only be accessed from addressing the SSPBUF register. Additionally, the SSP status register (SSPSTAT) indicates the various status conditions.

FIGURE 11-9: SSP BLOCK DIAGRAM (SPI MODE)(PIC16C66/67)



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11.4.2 ADDRESSING I²C DEVICES

There are two address formats. The simplest is the 7-bit address format with a R/$\overline{W}$ bit (Figure 11-15). The more complex is the 10-bit address with a R/$\overline{W}$ bit (Figure 11-16). For 10-bit address format, two bytes must be transmitted with the first five bits specifying this to be a 10-bit address.

FIGURE 11-15: 7-BIT ADDRESS FORMAT

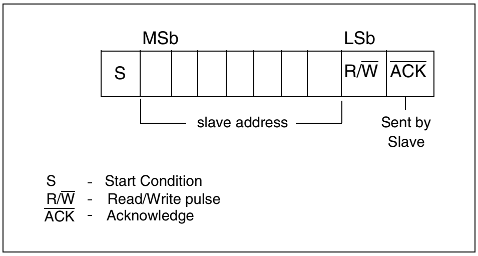
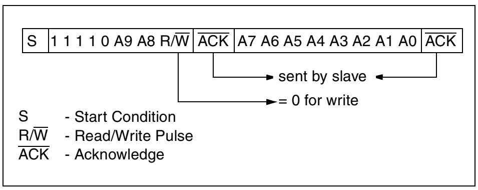


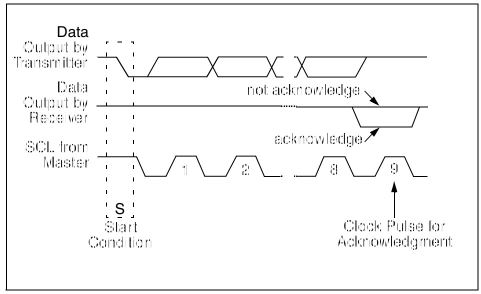
FIGURE 11-16: I²C 10-BIT ADDRESS FORMAT



11.4.3 TRANSFER ACKNOWLEDGE

All data must be transmitted per byte, with no limit to the number of bytes transmitted per data transfer. After each byte, the slave-receiver generates an acknowledge bit ($\overline{ACK}$) (Figure 11-17). When a slave-receiver doesn't acknowledge the slave address or received data, the master must abort the transfer. The slave must leave SDA high so that the master can generate the STOP condition (Figure 11-14).

FIGURE 11-17: SLAVE-RECEIVER ACKNOWLEDGE



If the master is receiving the data (master-receiver), it generates an acknowledge signal for each received byte of data, except for the last byte. To signal the end of data to the slave-transmitter, the master does not generate an acknowledge (not acknowledge). The slave then releases the SDA line so the master can generate the STOP condition. The master can also generate the STOP condition during the acknowledge pulse for valid termination of data transfer.

If the slave needs to delay the transmission of the next byte, holding the SCL line low will force the master into a wait state. Data transfer continues when the slave releases the SCL line. This allows the slave to move the received data or fetch the data it needs to transfer before allowing the clock to start. This wait state technique can also be implemented at the bit level, Figure 11-18. The slave will inherently stretch the clock, when it is a transmitter, but will not when it is a receiver. The slave will have to clear the SSPCON<4> bit to enable clock stretching when it is a receiver.

FIGURE 11-18: DATA TRANSFER WAIT STATE

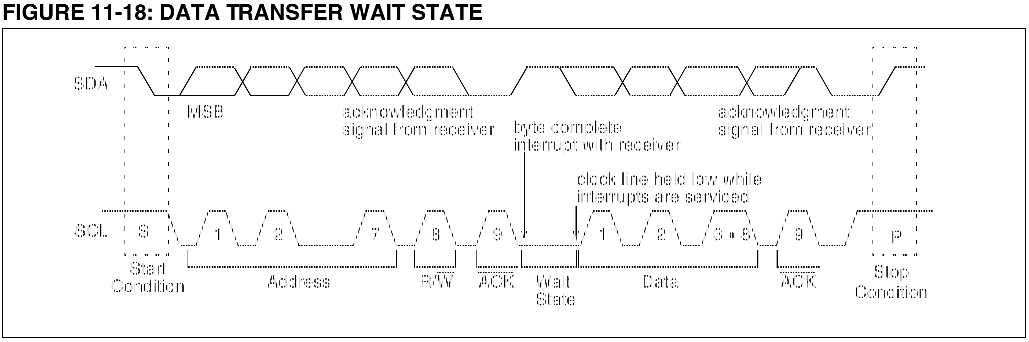


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FIGURE 11-27: OPERATION OF THE I²C MODULE IN IDLE_MODE, RCV_MODE OR XMIT_MODE

```
IDLE_MODE (7-bit):
if (Addr_match)          {     Set interrupt;
                               if (R/W = 1)     {     Send ACK = 0;
                                                      set XMIT_MODE;
                                                }
                               else if (R/W = 0) set RCV_MODE;
                         }

RCV_MODE:
if ((SSPBUF=Full) OR (SSPOV = 1))
        {     Set SSPOV;
              Do not acknowledge;
        }
else    {     transfer SSPSR → SSPBUF;
              send ACK = 0;
        }
Receive 8-bits in SSPSR;
Set interrupt;

XMIT_MODE:
While ((SSPBUF = Empty) AND (CKP=0)) Hold SCL Low;
Send byte;
Set interrupt;
if ( ACK Received = 1)   {     End of transmission;
                               Go back to IDLE_MODE;
                         }
else if ( ACK Received = 0)   Go back to XMIT_MODE;

IDLE_MODE (10-Bit):
If (High_byte_addr_match AND (R/W = 0))
        {     PRIOR_ADDR_MATCH = FALSE;
              Set interrupt;
              if ((SSPBUF = Full) OR ((SSPOV = 1))
                    {     Set SSPOV;
                          Do not acknowledge;
                    }
              else  {     Set UA = 1;
                          Send ACK = 0;
                          While (SSPADD not updated) Hold SCL low;
                          Clear UA = 0;
                          Receive Low_addr_byte;
                          Set interrupt;
                          Set UA = 1;
                          If (Low_byte_addr_match)
                                {     PRIOR_ADDR_MATCH = TRUE;
                                      Send ACK = 0;
                                      while (SSPADD not updated) Hold SCL low;
                                      Clear UA = 0;
                                      Set RCV_MODE;
                                }
                    }
        }
else if (High_byte_addr_match AND (R/W = 1)
        {     if (PRIOR_ADDR_MATCH)
                    {     send ACK = 0;
                          set XMIT_MODE;
                    }
              else PRIOR_ADDR_MATCH = FALSE;
        }
```


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13.8 Power-down Mode (SLEEP)

Applicable Devices														
61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67	

Power-down mode is entered by executing a `SLEEP` instruction.

If enabled, the Watchdog Timer will be cleared but keeps running, status bit $\overline{PD}$ (STATUS<3>) is cleared, status bit $\overline{TO}$ (STATUS<4>) is set, and the oscillator driver is turned off. The I/O ports maintain the status they had before the `SLEEP` instruction was executed (driving high, low, or hi-impedance).

For lowest current consumption in this mode, place all I/O pins at either V_{DD}, or V_{SS}, ensure no external circuitry is drawing current from the I/O pin, and disable external clocks. Pull all I/O pins, that are hi-impedance inputs, high or low externally to avoid switching currents caused by floating inputs. The T0CKI input should also be at V_{DD} or V_{SS} for lowest current consumption. The contribution from on-chip pull-ups on PORTB should be considered.

The $\overline{MCLR}$/V_{PP} pin must be at a logic high level (V_{IHMC}).

13.8.1 WAKE-UP FROM SLEEP

The device can wake from SLEEP through one of the following events:

1. External reset input on $\overline{MCLR}$/V_{PP} pin.
2. Watchdog Timer Wake-up (if WDT was enabled).
3. Interrupt from RB0/INT pin, RB port change, or some peripheral interrupts.

External $\overline{MCLR}$ Reset will cause a device reset. All other events are considered a continuation of program execution and cause a “wake-up”. The $\overline{TO}$ and $\overline{PD}$ bits in the STATUS register can be used to determine the cause of device reset. The $\overline{PD}$ bit, which is set on power-up is cleared when `SLEEP` is invoked. The $\overline{TO}$ bit is cleared if WDT time-out occurred (and caused wake-up).

The following peripheral interrupts can wake the device from SLEEP:

1. TMR1 interrupt. Timer1 must be operating as an asynchronous counter.
2. SSP (Start/Stop) bit detect interrupt.
3. SSP transmit or receive in slave mode (SPI/I^2C).
4. CCP capture mode interrupt.
5. Parallel Slave Port read or write.
6. USART TX or RX (synchronous slave mode).

Other peripherals can not generate interrupts since during SLEEP, no on-chip Q clocks are present.

When the `SLEEP` instruction is being executed, the next instruction (PC + 1) is pre-fetched. For the device to wake-up through an interrupt event, the corresponding interrupt enable bit must be set (enabled). Wake-up is regardless of the state of the GIE bit. If the GIE bit is clear (disabled), the device continues execution at the instruction after the `SLEEP` instruction. If the GIE bit is set (enabled), the device executes the instruction after the `SLEEP` instruction and then branches to the interrupt address (0004h). In cases where the execution of the instruction following `SLEEP` is not desirable, the user should have a `NOP` after the `SLEEP` instruction.

13.8.2 WAKE-UP USING INTERRUPTS

When global interrupts are disabled (GIE cleared) and any interrupt source has both its interrupt enable bit and interrupt flag bit set, one of the following will occur:

- If the interrupt occurs **before** the execution of a `SLEEP` instruction, the `SLEEP` instruction will complete as a NOP. Therefore, the WDT and WDT postscaler will not be cleared, the $\overline{TO}$ bit will not be set and $\overline{PD}$ bits will not be cleared.
- If the interrupt occurs **during or after** the execution of a `SLEEP` instruction, the device will immediately wake up from sleep. The `SLEEP` instruction will be completely executed before the wake-up. Therefore, the WDT and WDT postscaler will be cleared, the $\overline{TO}$ bit will be set and the $\overline{PD}$ bit will be cleared.

Even if the flag bits were checked before executing a `SLEEP` instruction, it may be possible for flag bits to become set before the `SLEEP` instruction completes. To determine whether a `SLEEP` instruction executed, test the $\overline{PD}$ bit. If the $\overline{PD}$ bit is set, the `SLEEP` instruction was executed as a NOP.

To ensure that the WDT is cleared, a `CLRWDT` instruction should be executed before a `SLEEP` instruction.

Applicable Devices	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67

NOTES:

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Applicable Devices	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67

17.0 ELECTRICAL CHARACTERISTICS FOR PIC16C62/64

Absolute Maximum Ratings †

Ambient temperature under bias .... -55°C to +85°C
Storage temperature .... -65°C to +150°C
Voltage on any pin with respect to V_{SS} (except V_{DD}, $\overline{MCLR}$, and RA4) .... -0.3V to (V_{DD} + 0.3V)
Voltage on V_{DD} with respect to V_{SS} .... -0.3V to +7.5V
Voltage on $\overline{MCLR}$ with respect to V_{SS} (Note 2) .... 0V to +14V
Voltage on RA4 with respect to Vss .... 0V to +14V
Total power dissipation (Note 1) 1.0W
Maximum current out of V_{SS} pin .... 300 mA
Maximum current into V_{DD} pin .... 250 mA
Input clamp current, I_{IK} (V_I < 0 or V_I > V_{DD}) .... ±20 mA
Output clamp current, I_{OK} (V_O < 0 or V_O > V_{DD}) .... ±20 mA
Maximum output current sunk by any I/O pin .... 25 mA
Maximum output current sourced by any I/O pin .... 25 mA
Maximum current sunk by PORTA, PORTB, and PORTE* (combined) .... 200 mA
Maximum current sourced by PORTA, PORTB, and PORTE* (combined) .... 200 mA
Maximum current sunk by PORTC and PORTD* (combined) .... 200 mA
Maximum current sourced by PORTC and PORTD* (combined) .... 200 mA

* PORTD and PORTE not available on the PIC16C62.

Note 1: Power dissipation is calculated as follows: $Pdis = V_{DD} \times \{I_{DD} - \sum I_{OH}\} + \sum \{(V_{DD}-V_{OH}) \times I_{OH}\} + \sum(V_{Ol} \times I_{OL})$

Note 2: Voltage spikes below V_{SS} at the $\overline{MCLR}$ pin, inducing currents greater than 80 mA, may cause latch-up. Thus, a series resistor of 50-100Ω should be used when applying a “low” level to the $\overline{MCLR}$ pin rather than pulling this pin directly to V_{SS}.

† NOTICE: Stresses above those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

TABLE 17-1: CROSS REFERENCE OF DEVICE SPECS FOR OSCILLATOR CONFIGURATIONS AND FREQUENCIES OF OPERATION (COMMERCIAL DEVICES)

OSC	PIC16C62-04 PIC16C64-04	PIC16C62-10 PIC16C64-10	PIC16C62-20 PIC16C64-20	PIC16LC62-04 PIC16LC64-04	JW Devices
RC	V_{DD}: 4.0V to 6.0V I_{DD}: 3.8 mA max. at 5.5V I_{PD}: 21 μA max. at 4V Freq:4 MHz max.	V_{DD}: 4.5V to 5.5V I_{DD}: 2.0 mA typ. at 5.5V I_{PD}: 1.5 μA typ. at 4V Freq:4 MHz max.	V_{DD}: 4.5V to 5.5V I_{DD}: 2.0 mA typ. at 5.5V I_{PD}: 1.5 μA typ. at 4V Freq:4 MHz max.	V_{DD}: 3.0V to 6.0V I_{DD}: 3.8 mA max. at 3.0V I_{PD}: 13.5 μA max. at 3V Freq: 4 MHz max.	V_{DD}: 4.0V to 6.0V I_{DD}: 3.8 mA max. at 5.5V I_{PD}: 21 μA max. at 4V Freq:4 MHz max.
XT	V_{DD}: 4.0V to 6.0V I_{DD}: 3.8 mA max. at 5.5V I_{PD}: 21 μA max. at 4V Freq:4 MHz max.	V_{DD}: 4.5V to 5.5V I_{DD}: 2.0 mA typ. at 5.5V I_{PD}: 1.5 μA typ. at 4V Freq:4 MHz max.	V_{DD}: 4.5V to 5.5V I_{DD}: 2.0 mA typ. at 5.5V I_{PD}: 1.5 μA typ. at 4V Freq:4 MHz max.	V_{DD}: 3.0V to 6.0V I_{DD}: 3.8 mA max. at 3.0V I_{PD}: 13.5 μA max. at 3.0V Freq: 4 MHz max.	V_{DD}: 4.0V to 6.0V I_{DD}: 3.8 mA max. at 5.5V I_{PD}: 21 μA max. at 4V Freq:4 MHz max.
HS	V_{DD}: 4.5V to 5.5V I_{DD}: 13.5 mA typ. at 5.5V I_{PD}: 1.5 μA typ. at 4.5V Freq:4 MHz max.	V_{DD}: 4.5V to 5.5V I_{DD}: 15 mA max. at 5.5V I_{PD}: 1.5 μA typ. at 4.5V Freq: 10 MHz max.	V_{DD}: 4.5V to 5.5V I_{DD}: 30 mA max. at 5.5V I_{PD}: 1.5 μA typ. at 4.5V Freq: 20 MHz max.	Not recommended for use in HS mode	V_{DD}: 4.5V to 5.5V I_{DD}: 30 mA max. at 5.5V I_{PD}: 1.5 μA typ. at 4.5V Freq: 20 MHz max.
LP	V_{DD}: 4.0V to 6.0V I_{DD}: 52.5 μA typ. at 32 kHz, 4.0V I_{PD}: 0.9 μA typ. at 4.0V Freq:200 kHz max.	Not recommended for use in LP mode	Not recommended for use in LP mode	V_{DD}: 3.0V to 6.0V I_{DD}: 48 μA max. at 32 kHz, 3.0V I_{PD}: 13.5 μA max. at 3.0V Freq:200 kHz max.	V_{DD}: 3.0V to 6.0V I_{DD}: 48 μA max. at 32 kHz, 3.0V I_{PD}:13.5 μA max. at 3.0V Freq:200 kHz max.

The shaded sections indicate oscillator selections which are tested for functionality, but not for MIN/MAX specifications. It is recommended that the user select the device type that ensures the specifications required.

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Applicable Devices	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67

17.2 DC Characteristics: PIC16LC62/64-04 (Commercial, Industrial)

DC CHARACTERISTICS		Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for industrial and 0°C ≤ TA ≤ +70°C for commercial					
Param No.	**Characteristic**	**Sym**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**
D001	Supply Voltage	VDD	3.0	-	6.0	V	LP, XT, RC osc configuration (DC - 4 MHz)
D002*	RAM Data Retention Voltage (Note 1)	VDR	-	1.5	-	V	
D003	VDD start voltage to ensure internal Power-on Reset signal	VPOR	-	VSS	-	V	See section on Power-on Reset for details
D004*	VDD rise rate to ensure internal Power-on Reset signal	SVDD	0.05	-	-	V/ms	See section on Power-on Reset for details
D010	Supply Current (Note 2, 5)	IDD	-	2.0	3.8	mA	XT, RC osc configuration FOSC = 4 MHz, VDD = 3.0V (Note 4)
D010A			-	22.5	48	μA	LP osc configuration FOSC = 32 kHz, VDD = 3.0V, WDT disabled
D020	Power-down Current (Note 3, 5)	IPD	-	7.5	30	μA	VDD = 3.0V, WDT enabled, -40°C to +85°C
D021			-	0.9	13.5	μA	VDD = 3.0V, WDT disabled, 0°C to +70°C
D021A			-	0.9	18	μA	VDD = 3.0V, WDT disabled, -40°C to +85°C

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: This is the limit to which VDD can be lowered without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading and switching rate, oscillator type, internal code execution pattern, and temperature also have an impact on the current consumption.
The test conditions for all IDD measurements in active operation mode are:
OSC1 = external square wave, from rail to rail; all I/O pins tristated, pulled to VDD
$\overline{\text{MCLR}}$ = VDD; WDT enabled/disabled as specified.

3: The power-down current in SLEEP mode does not depend on the oscillator type. Power-down current is measured with the part in SLEEP mode, with all I/O pins in hi-impedance state and tied to VDD and VSS.

4: For RC osc configuration, current through Rext is not included. The current through the resistor can be estimated by the formula Ir = VDD/2Rext (mA) with Rext in kOhm.

5: Timer1 oscillator (when enabled) adds approximately 20 μA to the specification. This value is from characterization and is for design guidance only. This is not tested.

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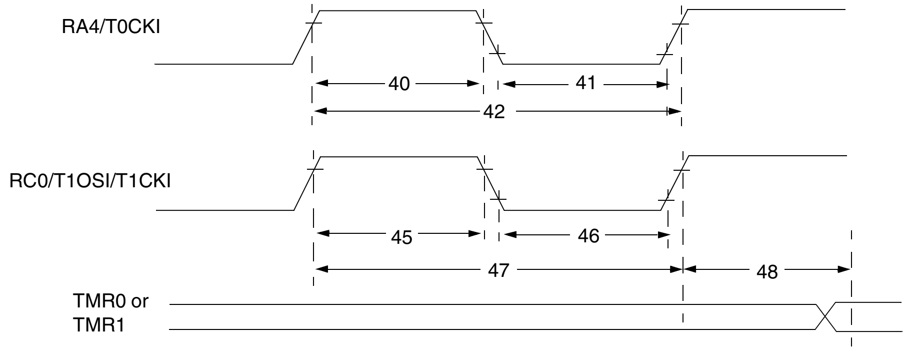
Applicable Devices	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67

FIGURE 17-5: TIMER0 AND TIMER1 EXTERNAL CLOCK TIMINGS



Note: Refer to Figure 17-1 for load conditions.

TABLE 17-5: TIMER0 AND TIMER1 EXTERNAL CLOCK REQUIREMENTS

Param No.	Sym	Characteristic			Min	Typ†	Max	Units	Conditions
40*	Tt0H	T0CKI High Pulse Width	No Prescaler		$0.5T_{CY} + 20$	—	—	ns	Must also meet parameter 42
			With Prescaler		10	—	—	ns	
41*	Tt0L	T0CKI Low Pulse Width	No Prescaler		$0.5T_{CY} + 20$	—	—	ns	Must also meet parameter 42
			With Prescaler		10	—	—	ns	
42*	Tt0P	T0CKI Period	No Prescaler		$T_{CY} + 40$	—	—	ns	
			With Prescaler		Greater of: 20 or $\frac{T_{CY} + 40}{N}$	—	—	ns	N = prescale value (2, 4, ..., 256)
45*	Tt1H	T1CKI High Time	Synchronous, Prescaler = 1		$0.5T_{CY} + 20$	—	—	ns	Must also meet parameter 47
			Synchronous, Prescaler = 2,4,8	PIC16**C**6X	15	—	—	ns	
				PIC16**LC**6X	25	—	—	ns	
			Asynchronous	PIC16**C**6X	30	—	—	ns	
				PIC16**LC**6X	50	—	—	ns	
46*	Tt1L	T1CKI Low Time	Synchronous, Prescaler = 1		$0.5T_{CY} + 20$	—	—	ns	Must also meet parameter 47
			Synchronous, Prescaler = 2,4,8	PIC16**C**6X	15	—	—	ns	
				PIC16**LC**6X	25	—	—	ns	
			Asynchronous	PIC16**C**6X	30	—	—	ns	
				PIC16**LC**6X	50	—	—	ns	
47*	Tt1P	T1CKI input period	Synchronous	PIC16**C**6X	Greater of: 30 OR $\frac{T_{CY} + 40}{N}$	—	—	ns	N = prescale value (1, 2, 4, 8)
				PIC16**LC**6X	Greater of: 50 OR $\frac{T_{CY} + 40}{N}$				N = prescale value (1, 2, 4, 8)
			Asynchronous	PIC16**C**6X	60	—	—	ns	
				PIC16**LC**6X	100	—	—	ns	
	Ft1	Timer1 oscillator input frequency range (oscillator enabled by setting bit T1OSCEN)			DC	—	200	kHz	
48	TCKEZtmr1	Delay from external clock edge to timer increment			2Tosc	—	7Tosc	—	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

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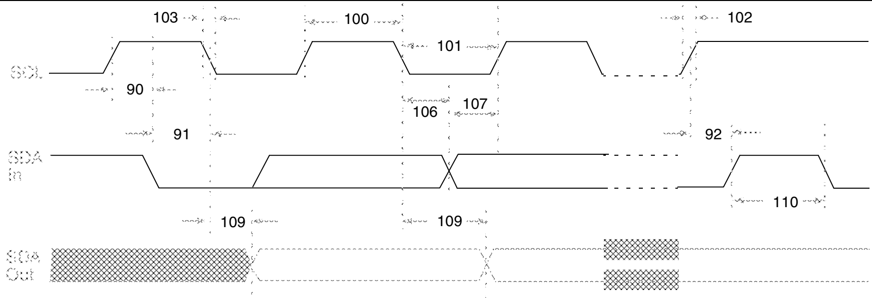
Applicable Devices	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67

FIGURE 17-10: I²C BUS DATA TIMING



Note: Refer to Figure 17-1 for load conditions

TABLE 17-10: I²C BUS DATA REQUIREMENTS

Parameter No.	Sym	Characteristic		Min	Max	Units	Conditions
100	THIGH	Clock high time	100 kHz mode	4.0	—	μs	Device must operate at a minimum of 1.5 MHz
			400 kHz mode	0.6	—	μs	Device must operate at a minimum of 10 MHz
			SSP Module	1.5TCY	—		
101	TLOW	Clock low time	100 kHz mode	4.7	—	μs	Device must operate at a minimum of 1.5 MHz
			400 kHz mode	1.3	—	μs	Device must operate at a minimum of 10 MHz
			SSP Module	1.5TCY	—		
102	TR	SDA and SCL rise time	100 kHz mode	—	1000	ns	
			400 kHz mode	20 + 0.1Cb	300	ns	Cb is specified to be from 10 to 400 pF
103	TF	SDA and SCL fall time	100 kHz mode	—	300	ns	
			400 kHz mode	20 + 0.1Cb	300	ns	Cb is specified to be from 10 to 400 pF
90	TSU:STA	START condition setup time	100 kHz mode	4.7	—	μs	Only relevant for repeated START condition
			400 kHz mode	0.6	—	μs	
91	THD:STA	START condition hold time	100 kHz mode	4.0	—	μs	After this period the first clock pulse is generated
			400 kHz mode	0.6	—	μs	
106	THD:DAT	Data input hold time	100 kHz mode	0	—	ns	
			400 kHz mode	0	0.9	μs	
107	TSU:DAT	Data input setup time	100 kHz mode	250	—	ns	Note 2
			400 kHz mode	100	—	ns	
92	TSU:STO	STOP condition setup time	100 kHz mode	4.7	—	μs	
			400 kHz mode	0.6	—	μs	
109	TAA	Output valid from clock	100 kHz mode	—	3500	ns	Note 1
			400 kHz mode	—	—	ns	
110	TBUF	Bus free time	100 kHz mode	4.7	—	μs	Time the bus must be free before a new transmission can start
			400 kHz mode	1.3	—	μs	
	Cb	Bus capacitive loading		—	400	pF	

Note 1: As a transmitter, the device must provide this internal minimum delay time to bridge the undefined region (min. 300 ns) of the falling edge of SCL to avoid unintended generation of START or STOP conditions.

2: A fast-mode (400 kHz) I²C-bus device can be used in a standard-mode (100 kHz) I²C-bus system, but the requirement tsu;DAT ≥ 250 ns must then be met. This will automatically be the case if the device does not stretch the LOW period of the SCL signal. If such a device does stretch the LOW period of the SCL signal, it must output the next data bit to the SDA line TR max. + tsu;DAT = 1000 + 250 = 1250 ns (according to the standard-mode I²C bus specification) before the SCL line is released.

Applicable Devices	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67

18.2 DC Characteristics: PIC16LC62A/R62/64A/R64-04 (Commercial, Industrial)

DC CHARACTERISTICS		**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial and 0°C ≤ TA ≤ +70°C for commercial					
Param No.	**Characteristic**	**Sym**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**
D001	Supply Voltage	VDD	2.5	-	6.0	V	LP, XT, RC osc configuration (DC - 4 MHz)
D002*	RAM Data Retention Voltage (Note 1)	VDR	-	1.5	-	V	
D003	VDD start voltage to ensure internal Power-on Reset signal	VPOR	-	VSS	-	V	See section on Power-on Reset for details
D004*	VDD rise rate to ensure internal Power-on Reset signal	SVDD	0.05	-	-	V/ms	See section on Power-on Reset for details
D005	Brown-out Reset Voltage	BVDD	3.7	4.0	4.3	V	BODEN bit in configuration word enabled
D010	Supply Current (Note 2, 5)	IDD	-	2.0	3.8	mA	XT, RC osc configuration FOSC = 4 MHz, VDD = 3.0V (Note 4)
D010A			-	22.5	48	μA	LP osc configuration FOSC = 32 kHz, VDD = 3.0V, WDT disabled
D015*	Brown-out Reset Current (Note 6)	ΔIBOR	-	350	425	μA	BOR enabled, VDD = 5.0V
D020	Power-down Current (Note 3, 5)	IPD	-	7.5	30	μA	VDD = 3.0V, WDT enabled, -40°C to +85°C
D021			-	0.9	5	μA	VDD = 3.0V, WDT disabled, 0°C to +70°C
D021A			-	0.9	5	μA	VDD = 3.0V, WDT disabled, -40°C to +85°C
D023*	Brown-out Reset Current (Note 6)	ΔIBOR	-	350	425	μA	BOR enabled, VDD = 5.0V

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: This is the limit to which VDD can be lowered without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading and switching rate, oscillator type, internal code execution pattern, and temperature also have an impact on the current consumption.
The test conditions for all IDD measurements in active operation mode are:
OSC1 = external square wave, from rail to rail; all I/O pins tristated, pulled to VDD
$\overline{\text{MCLR}}$ = VDD; WDT enabled/disabled as specified.

3: The power-down current in SLEEP mode does not depend on the oscillator type. Power-down current is measured with the part in SLEEP mode, with all I/O pins in hi-impedance state and tied to VDD and VSS.

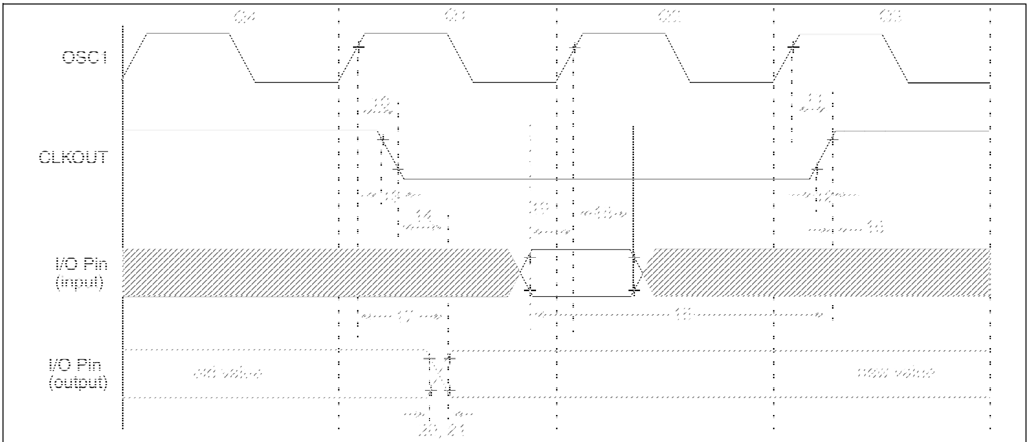
4: For RC osc configuration, current through Rext is not included. The current through the resistor can be estimated by the formula Ir = VDD/2Rext (mA) with Rext in kOhm.

5: Timer1 oscillator (when enabled) adds approximately 20 μA to the specification. This value is from characterization and is for design guidance only. This is not tested.

6: The Δ current is the additional current consumed when this peripheral is enabled. This current should be added to the base IDD or IPD measurement.

Applicable Devices	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67

FIGURE 20-3: CLKOUT AND I/O TIMING



Note: Refer to Figure 20-1 for load conditions.

TABLE 20-3: CLKOUT AND I/O TIMING REQUIREMENTS

Parameter No.	Sym	Characteristic		Min	Typ†	Max	Units	Conditions
10*	TosH2ckL	OSC1↑ to CLKOUT↓		—	75	200	ns	Note 1
11*	TosH2ckH	OSC1↑ to CLKOUT↑		—	75	200	ns	Note 1
12*	TckR	CLKOUT rise time		—	35	100	ns	Note 1
13*	TckF	CLKOUT fall time		—	35	100	ns	Note 1
14*	TckL2ioV	CLKOUT ↓ to Port out valid		—	—	0.5TCY + 20	ns	Note 1
15*	TioV2ckH	Port in valid before CLKOUT ↑		Tosc + 200	—	—	ns	Note 1
16*	TckH2ioI	Port in hold after CLKOUT ↑		0	—	—	ns	Note 1
17*	TosH2ioV	OSC1↑ (Q1 cycle) to Port out valid		—	50	150	ns	
18*	TosH2ioI	OSC1↑ (Q2 cycle) to Port input invalid (I/O in hold time)	PIC16**C**63/65A	100	—	—	ns	
			PIC16**LC**63/65A	200	—	—	ns	
19*	TioV2osH	Port input valid to OSC1↑ (I/O in setup time)		0	—	—	ns	
20*	TioR	Port output rise time	PIC16**C**63/65A	—	10	40	ns	
			PIC16**LC**63/65A	—	—	80	ns	
21*	TioF	Port output fall time	PIC16**C**63/65A	—	10	40	ns	
			PIC16**LC**63/65A	—	—	80	ns	
22††*	Tinp	INT pin high or low time		TCY	—	—	ns	
23††*	Trbp	RB7:RB4 change INT high or low time		TCY	—	—	ns	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

†† These parameters are asynchronous events not related to any internal clock edge.

Note 1: Measurements are taken in RC Mode where CLKOUT output is 4 x TOSC.

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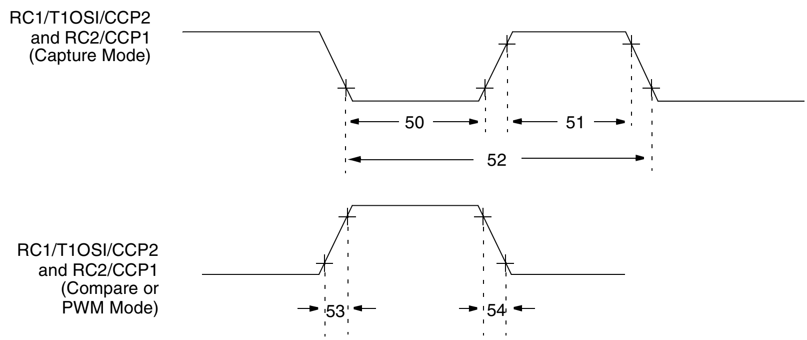
Applicable Devices	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67

FIGURE 20-7: CAPTURE/COMPARE/PWM TIMINGS (CCP1 AND CCP2)



Note: Refer to Figure 20-1 for load conditions.

TABLE 20-6: CAPTURE/COMPARE/PWM REQUIREMENTS (CCP1 AND CCP2)

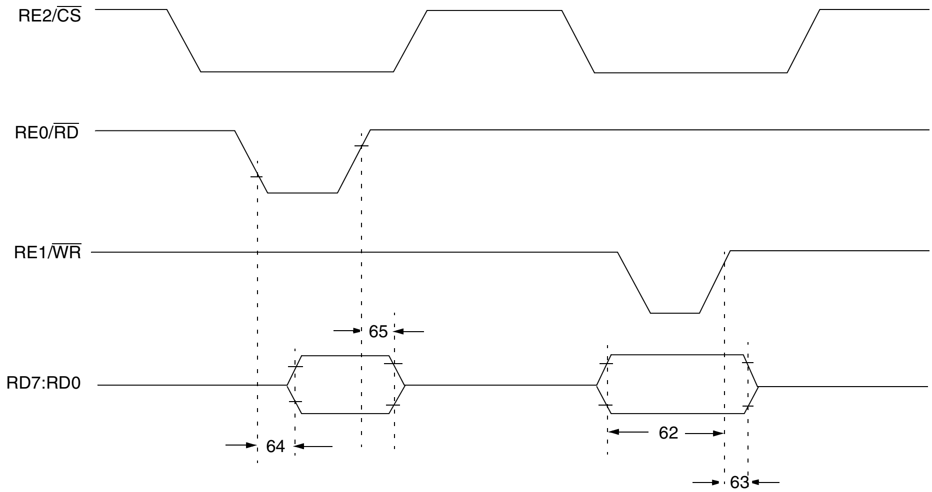
Parameter No.	Sym	Characteristic			Min	Typ†	Max	Units	Conditions
50*	TccL	CCP1 and CCP2 input low time	No Prescaler		0.5TCY + 20	—	—	ns	
			With Prescaler	PIC16**C**63/65A	10	—	—	ns	
				PIC16**LC**63/65A	20	—	—	ns	
51*	TccH	CCP1 and CCP2 input high time	No Prescaler		0.5TCY + 20	—	—	ns	
			With Prescaler	PIC16**C**63/65A	10	—	—	ns	
				PIC16**LC**63/65A	20	—	—	ns	
52*	TccP	CCP1 and CCP2 input period			$\frac{3T_{CY} + 40}{N}$	—	—	ns	N = prescale value (1,4, or 16)
53*	TccR	CCP1 and CCP2 output rise time		PIC16**C**63/65A	—	10	25	ns	
				PIC16**LC**63/65A	—	25	45	ns	
54*	TccF	CCP1 and CCP2 output fall time		PIC16**C**63/65A	—	10	25	ns	
				PIC16**LC**63/65A	—	25	45	ns	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Applicable Devices	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67

FIGURE 22-8: PARALLEL SLAVE PORT TIMING (PIC16C67)



Note: Refer to Figure 22-1 for load conditions

TABLE 22-7: PARALLEL SLAVE PORT REQUIREMENTS (PIC16C67)

Parameter No.	Sym	Characteristic		Min	Typ†	Max	Units	Conditions
62*	TdtV2wrH	Data in valid before $\overline{WR}$↑ or $\overline{CS}$↑ (setup time)		20	—	—	ns	
				25	—	—	ns	Extended Range Only
63*	TwrH2dtI	$\overline{WR}$↑ or $\overline{CS}$↑ to data–in invalid (hold time)	PIC16**C**67	20	—	—	ns	
			PIC16**LC**67	35	—	—	ns	
64	TrdL2dtV	$\overline{RD}$↓ and $\overline{CS}$↓ to data–out valid		—	—	80	ns	
				—	—	90	ns	Extended Range Only
65*	TrdH2dtI	$\overline{RD}$↑ or $\overline{CS}$↑ to data–out invalid		10	—	30	ns	

* These parameters are characterized but not tested.
† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

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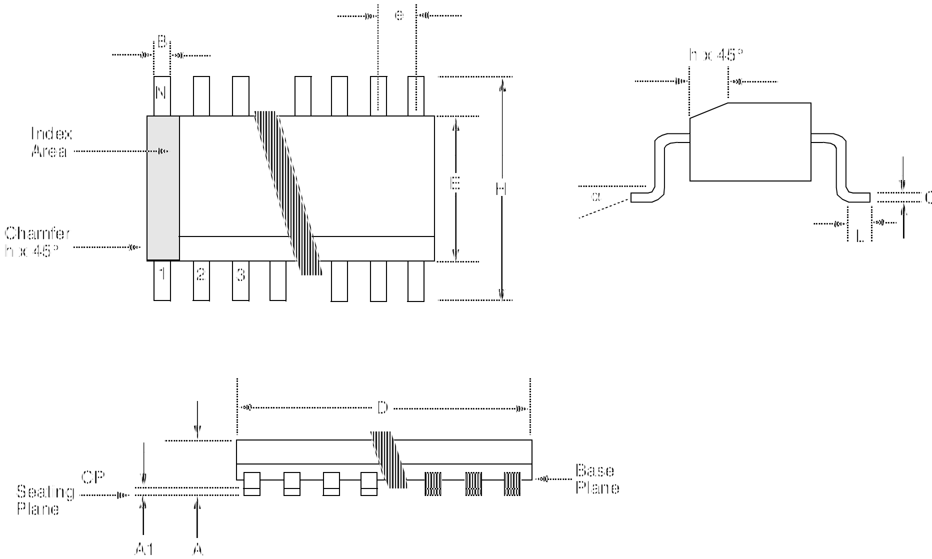
24.4 18-Lead Plastic Surface Mount (SOIC - Wide, 300 mil Body) (SO)

Note:	For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Package Group: Plastic SOIC (SO)						
	Millimeters			Inches		
Symbol	Min	Max	Notes	Min	Max	Notes
α	0°	8°		0°	8°	
A	2.362	2.642		0.093	0.104	
A1	0.101	0.300		0.004	0.012	
B	0.355	0.483		0.014	0.019	
C	0.241	0.318		0.009	0.013	
D	11.353	11.735		0.447	0.462	
E	7.416	7.595		0.292	0.299	
e	1.270	1.270	**Reference**	0.050	0.050	**Reference**
H	10.007	10.643		0.394	0.419	
h	0.381	0.762		0.015	0.030	
L	0.406	1.143		0.016	0.045	
N	18	18		18	18	
CP	–	0.102		–	0.004	

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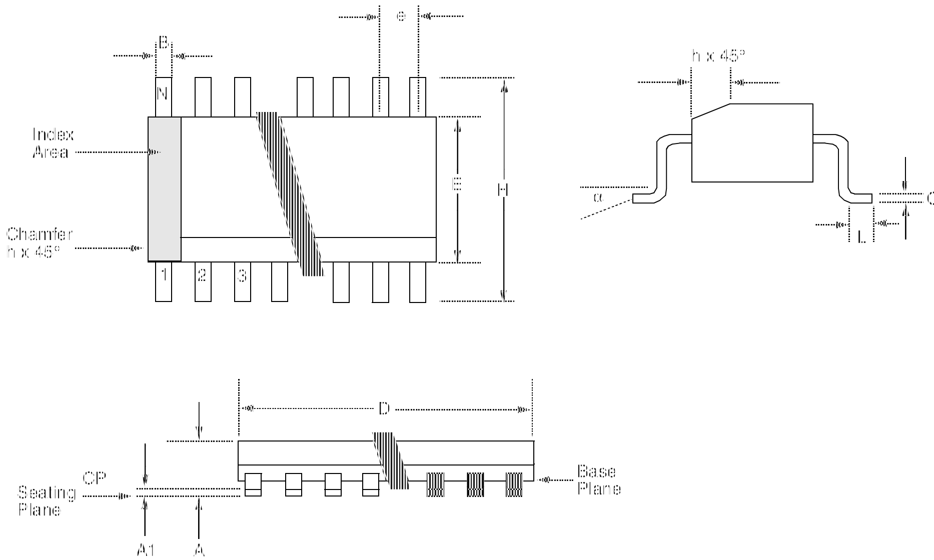
24.5 28-Lead Plastic Surface Mount (SOIC - Wide, 300 mil Body) (SO)

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Package Group: Plastic SOIC (SO)						
	Millimeters			Inches		
Symbol	Min	Max	Notes	Min	Max	Notes
α	0°	8°		0°	8°	
A	2.362	2.642		0.093	0.104	
A1	0.101	0.300		0.004	0.012	
B	0.355	0.483		0.014	0.019	
C	0.241	0.318		0.009	0.013	
D	17.703	18.085		0.697	0.712	
E	7.416	7.595		0.292	0.299	
e	1.270	1.270	**Typical**	0.050	0.050	**Typical**
H	10.007	10.643		0.394	0.419	
h	0.381	0.762		0.015	0.030	
L	0.406	1.143		0.016	0.045	
N	28	28		28	28	
CP	–	0.102		–	0.004	

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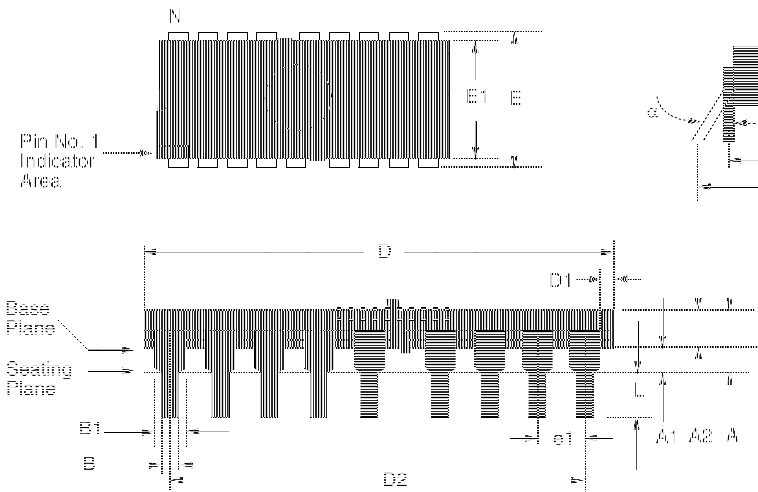
24.7 28-Lead Ceramic CERDIP Dual In-line with Window (300 mil)) (JW)

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Package Group: Ceramic CERDIP Dual In-Line (CDP)						
	Millimeters			Inches		
Symbol	Min	Max	Notes	Min	Max	Notes
α	0°	10°		0°	10°	
A	3.30	5.84		.130	0.230	
A1	0.38	—		0.015	—	
A2	2.92	4.95		0.115	0.195	
B	0.35	0.58		0.014	0.023	
B1	1.14	1.78	**Typical**	0.045	0.070	**Typical**
C	0.20	0.38	**Typical**	0.008	0.015	**Typical**
D	34.54	37.72		1.360	1.485	
D2	32.97	33.07	**Reference**	1.298	1.302	**Reference**
E	7.62	8.25		0.300	0.325	
E1	6.10	7.87		0.240	0.310	
e	2.54	2.54	**Typical**	0.100	0.100	**Typical**
eA	7.62	7.62	**Reference**	0.300	0.300	**Reference**
eB	—	11.43		—	0.450	
L	2.92	5.08		0.115	0.200	
N	28	28		28	28	
D1	0.13	—		0.005	—	

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F.5 PIC16C55X Family of Devices

		PIC16C554	PIC16C556(1)	PIC16C558
Clock	Maximum Frequency of Operation (MHz)	20	20	20
Memory	EPROM Program Memory (x14 words)	512	1K	2K
	Data Memory (bytes)	80	80	128
Peripherals	Timer Module(s)	TMR0	TMR0	TMR0
	Comparators(s)	—	—	—
	Internal Reference Voltage	—	—	—
Features	Interrupt Sources	3	3	3
	I/O Pins	13	13	13
	Voltage Range (Volts)	2.5-6.0	2.5-6.0	2.5-6.0
	Brown-out Reset	—	—	—
	Packages	18-pin DIP, SOIC; 20-pin SSOP	18-pin DIP, SOIC; 20-pin SSOP	18-pin DIP, SOIC; 20-pin SSOP

All PIC16/17 Family devices have Power-on Reset, selectable Watchdog Timer, selectable code protect and high I/O current capability. All PIC16C5XX Family devices use serial programming with clock pin RB6 and data pin RB7.
Note 1: Please contact your local Microchip sales office for availability of these devices.

F.6 PIC16C62X and PIC16C64X Family of Devices

		PIC16C620	PIC16C621	PIC16C622	PIC16C642	PIC16C662
Clock	Maximum Frequency of Operation (MHz)	20	20	20	20	20
Memory	EPROM Program Memory (x14 words)	512	1K	2K	4K	4K
	Data Memory (bytes)	80	80	128	176	176
Peripherals	Timer Module(s)	TMR0	TMR0	TMR0	TMR0	TMR0
	Comparators(s)	2	2	2	2	2
	Internal Reference Voltage	Yes	Yes	Yes	Yes	Yes
Features	Interrupt Sources	4	4	4	4	5
	I/O Pins	13	13	13	22	33
	Voltage Range (Volts)	2.5-6.0	2.5-6.0	2.5-6.0	3.0-6.0	3.0-6.0
	Brown-out Reset	Yes	Yes	Yes	Yes	Yes
	Packages	18-pin DIP, SOIC; 20-pin SSOP	18-pin DIP, SOIC; 20-pin SSOP	18-pin DIP, SOIC; 20-pin SSOP	28-pin PDIP, SOIC, Windowed CDIP	40-pin PDIP, Windowed CDIP; 44-pin PLCC, MQFP

All PIC16/17 Family devices have Power-on Reset, selectable Watchdog Timer, selectable code protect and high I/O current capability. All PIC16C62X and PIC16C64X Family devices use serial programming with clock pin RB6 and data pin RB7.

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PIN COMPATIBILITY

Devices that have the same package type and VDD, VSS and $\overline{MCLR}$ pin locations are said to be pin compatible. This allows these different devices to operate in the same socket. Compatible devices may only requires minor software modification to allow proper operation in the application socket (ex., PIC16C56 and PIC16C61 devices). Not all devices in the same package size are pin compatible; for example, the PIC16C62 is compatible with the PIC16C63, but not the PIC16C55.

Pin compatibility does not mean that the devices offer the same features. As an example, the PIC16C54 is pin compatible with the PIC16C71, but does not have an A/D converter, weak pull-ups on PORTB, or interrupts.

TABLE F-1: PIN COMPATIBLE DEVICES

Pin Compatible Devices	Package
PIC12C508, PIC12C509, PIC12C671, PIC12C672	8-pin
PIC16C154, PIC16CR154, PIC16C156, PIC16CR156, PIC16C158, PIC16CR158, PIC16C52, PIC16C54, PIC16C54A, PIC16CR54A, PIC16C56, PIC16C58A, PIC16CR58A, PIC16C61, PIC16C554, PIC16C556, PIC16C558 PIC16C620, PIC16C621, PIC16C622 PIC16C641, PIC16C642, PIC16C661, PIC16C662 PIC16C710, PIC16C71, PIC16C711, PIC16C715 PIC16F83, PIC16CR83, PIC16F84A, PIC16CR84	18-pin, 20-pin
PIC16C55, PIC16C57, PIC16CR57B	28-pin
PIC16CR62, PIC16C62A, PIC16C63, PIC16CR63, PIC16C66, PIC16C72, PIC16C73A, PIC16C76	28-pin
PIC16CR64, PIC16C64A, PIC16C65A, PIC16CR65, PIC16C67, PIC16C74A, PIC16C77	40-pin
PIC17CR42, PIC17C42A, PIC17C43, PIC17CR43, PIC17C44	40-pin
PIC16C923, PIC16C924	64/68-pin
PIC17C756, PIC17C752	64/68-pin